

Power Supply Design Seminar

Introduction to the trans-inductor voltage regulator (TLVR)

Authors

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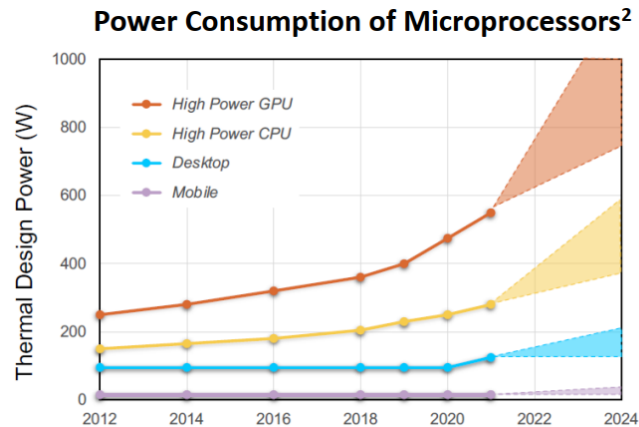
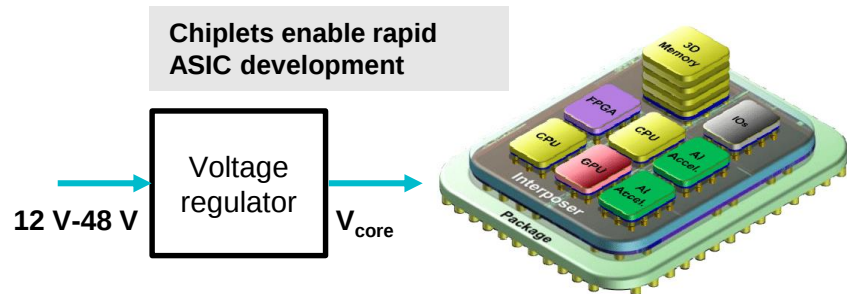


Agenda/overview

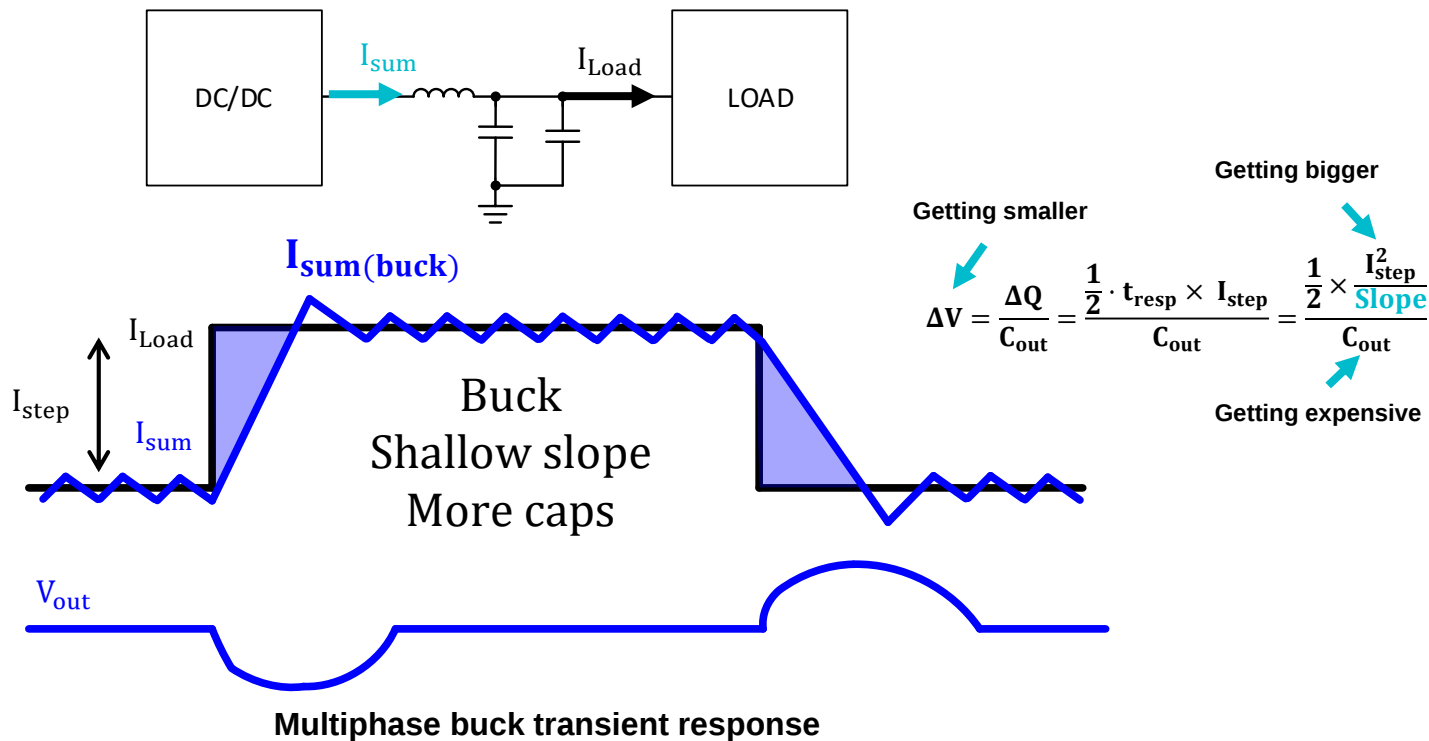
- Background and motivation
- Transinductor voltage regulator (TLVR) topology introduction
- Practical considerations
- Conclusion

Voltage regulator design challenges

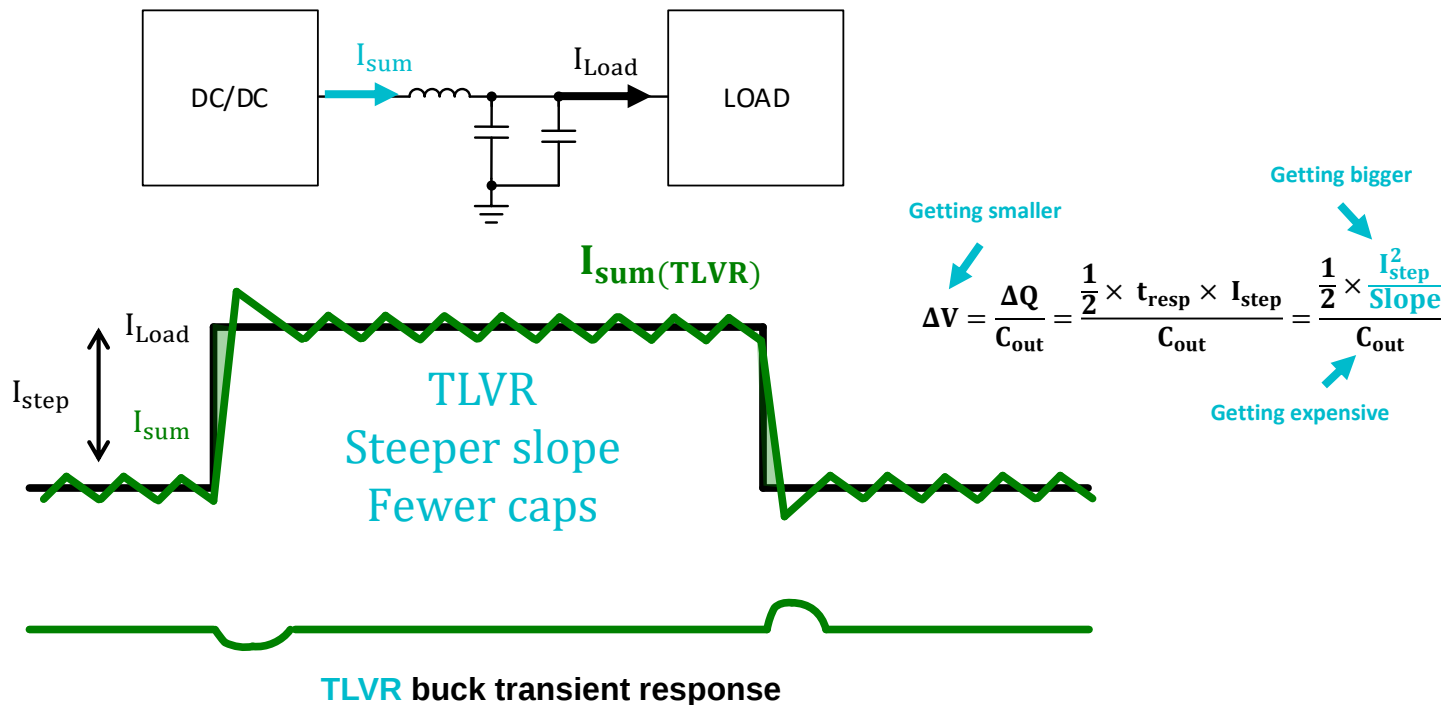
- **Silicon technology continues to shrink** (but this is slowing)
3-nm digital → lower
- Application-specific integrated circuit (ASIC) **operating voltages remain** 0.7 V to 1.0 V (up to 1.8 V)
- High-core-count designs and chiplet revolution driving **rapid increase in operating currents**
>1,000-A designs
- Extreme load transient requirements
1,000 A/μs, ±3%



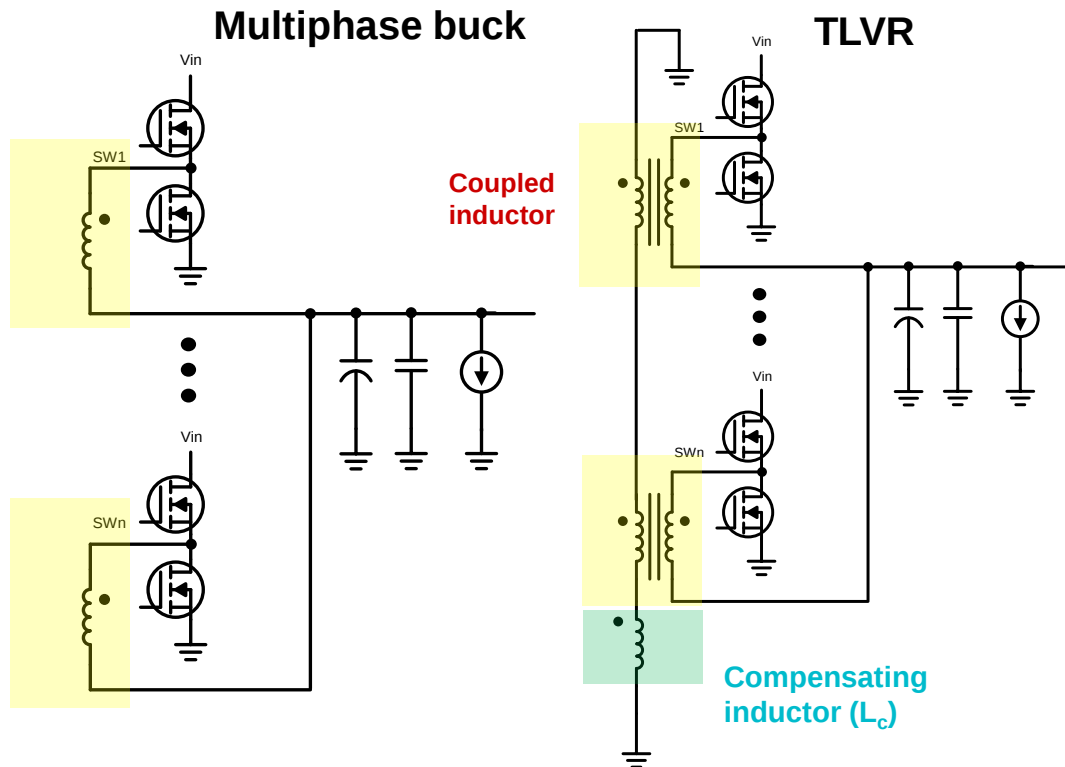
Motivation for TLVR: Improving transient response



Motivation for TLVR: Improving transient response



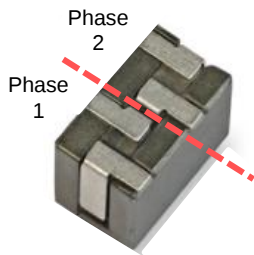
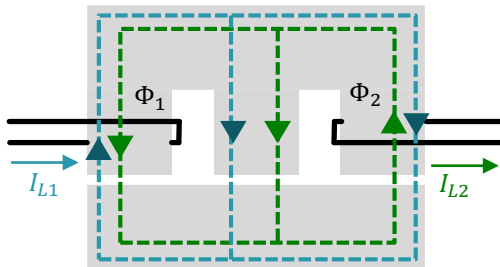
Buck converter vs. TLVR topology



- **Buck-derived** topology optimized for fast transient response
- TLVR is a new twist on the coupled-inductor buck converter
- **When it makes sense:**
 - High phase count (>six phases)
 - High di/dt load transient
 - Moderate voltage ripple

Traditional coupled inductor

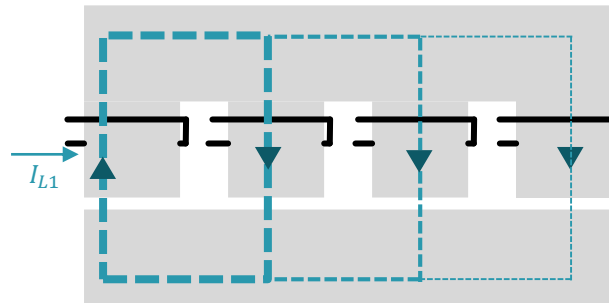
Traditional coupled inductor (two phase)



Two-phase coupled inductor
Source: Eaton

- Multiple windings share a single core
- Typical coupling coefficient: ≈ 0.5 to 0.7
- Higher power density
- Customized design for phase count/layouts

Difficult to extend to higher phases

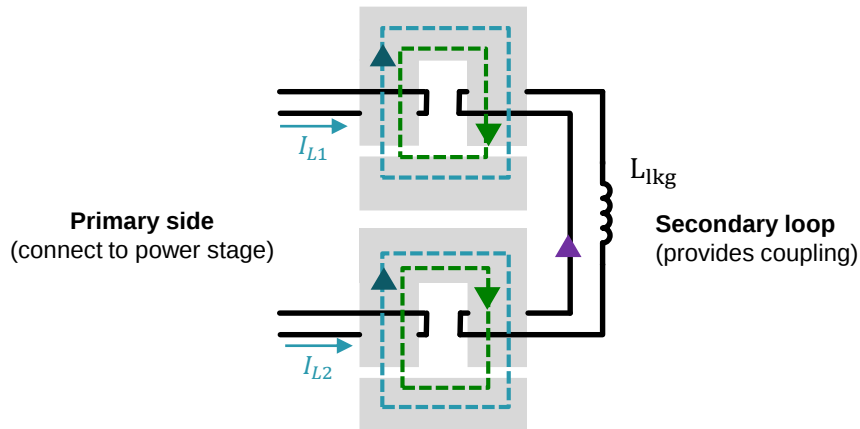


- **Challenge:** Symmetry is required for equal coupling among phases
- **Challenge:** Complex geometry required to maintain symmetry at higher phase counts

Coupling allows high steady state inductance (low ripple) and low transient inductance (fast transient)

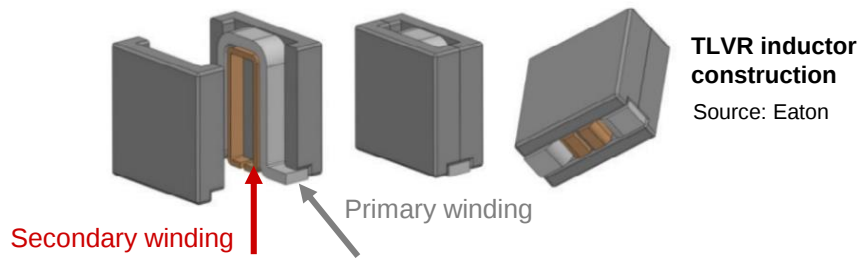
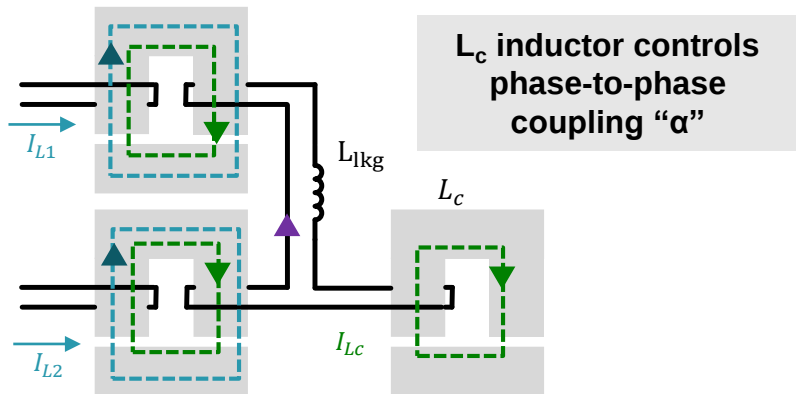
Indirect-coupled inductor

Indirect-coupled inductor (two phase)



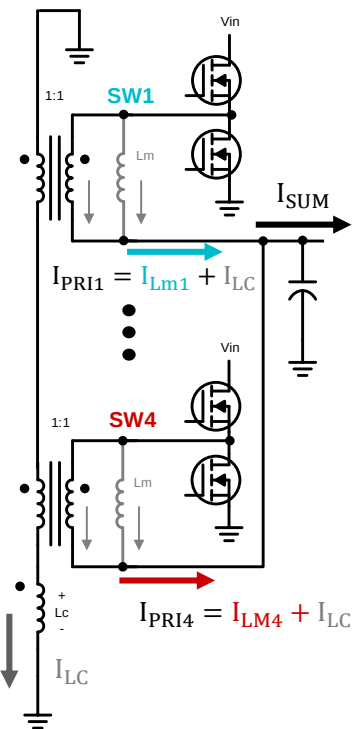
- Phases are coupled symmetrically without a sharing core
- **Simple core geometry, scalable solution**
- **Challenging to control coupling**

TLVR: Indirect-coupling and compensating inductor (L_c)



TLVR topology overview

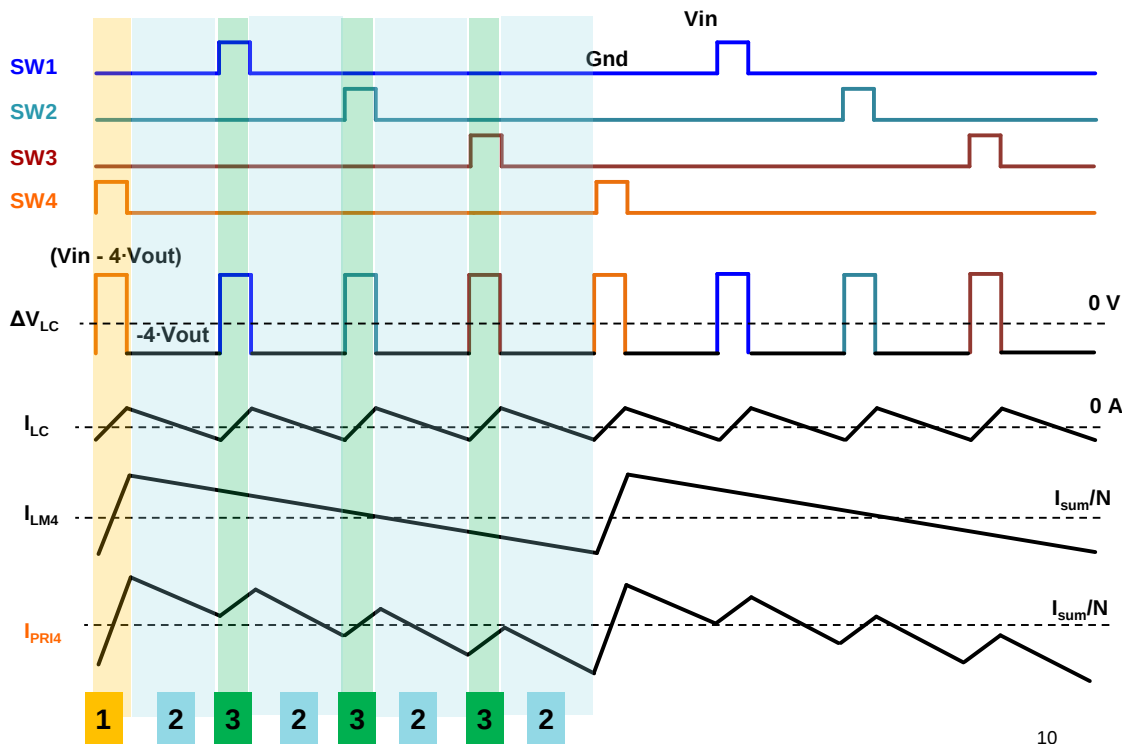
TLVR operating principle: Steady state



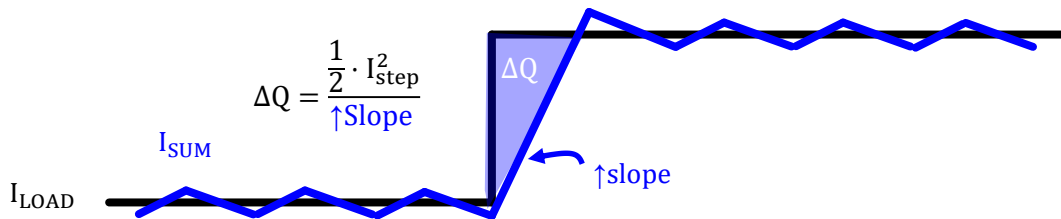
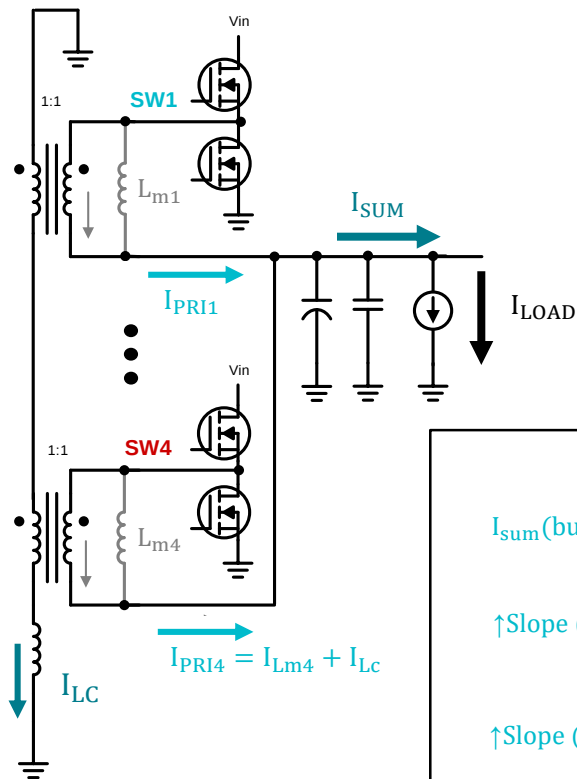
Phase current description (I_{PRI4})

1. This phase (SW4) is on; all others are off
 I_{LM4} increases
 I_{LC} increases
2. All phases are off
 I_{LM4} decreases
 I_{LC} decreases
3. This phase (SW4) is off, but others are on
 I_{LM} decreases
 I_{LC} increases

TLVR steady-state operation (four-phase example, no overlap)



TLVR operating principle: Transient step-up



Controller **turns on multiple phases** in response.

N_{ON} phases are on, N_{OFF} phases are off

Multiphase buck

$$I_{sum}(\text{buck}) = I_{L1} + I_{L2} + \dots$$

$$\uparrow \text{Slope}(\text{buck}) = \frac{\Delta V_{L1}}{L} + \frac{\Delta V_{L2}}{L} + \dots$$

$$\uparrow \text{Slope}(\text{buck}) \approx N_{on} \left(\frac{V_{in} - V_{out}}{L} \right) - N_{off} \left(\frac{V_{out}}{L} \right)$$

TLVR

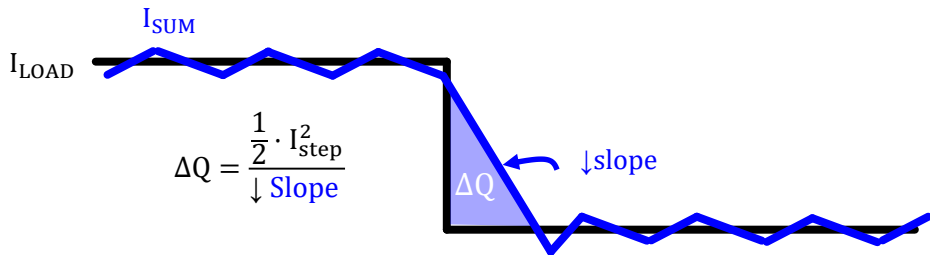
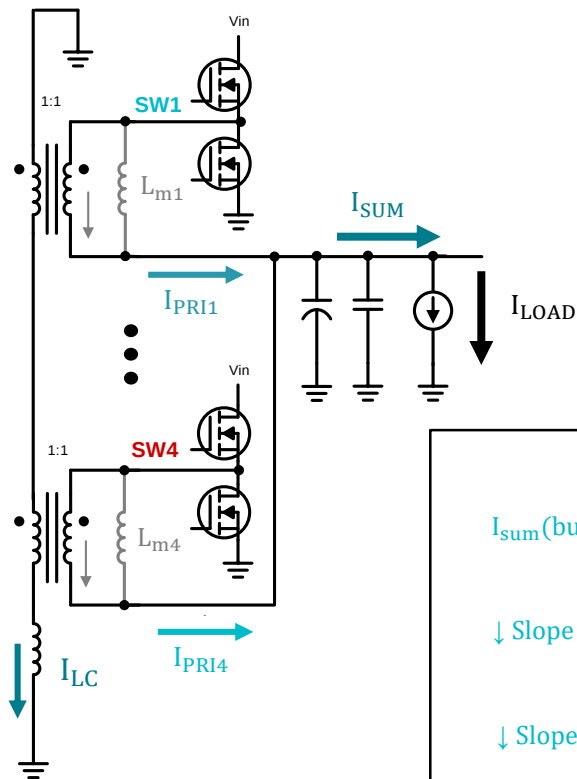
$$I_{sum}(\text{TLVR}) = I_{pri1} + I_{pri2} + \dots$$

$$I_{sum}(\text{TLVR}) = (I_{Lm1} + I_{Lc}) + (I_{Lm2} + I_{Lc}) + \dots$$

$$\uparrow \text{Slope}(\text{TLVR}) = \left(\frac{\Delta V_{L1}}{L_m} + \frac{\Delta V_{Lc}}{L_c} \right) + \left(\frac{\Delta V_{L2}}{L_m} + \frac{\Delta V_{Lc}}{L_c} \right) + \dots$$

$$\uparrow \text{Slope}(\text{TLVR}) \approx \uparrow \text{Slope}(\text{buck}) + N_{total} \left[\frac{N_{on} \cdot V_{in} - N_{total} \times V_{out}}{L_c} \right]$$

TLVR operating principle: Transient step-down



Controller **turns off all phases** in response

N_{TOTAL} phases are off

Multiphase buck

$$I_{sum}(buck) = I_{L1} + I_{L2} + \dots$$

$$\downarrow \text{Slope (buck)} = \frac{\Delta V_{L1}}{L} + \frac{\Delta V_{L2}}{L} + \dots$$

$$\downarrow \text{Slope(buck)} \approx -N_{total} \left(\frac{V_{out}}{L} \right)$$

TLVR

$$I_{sum}(TLVR) = I_{pri1} + I_{pri2} + \dots$$

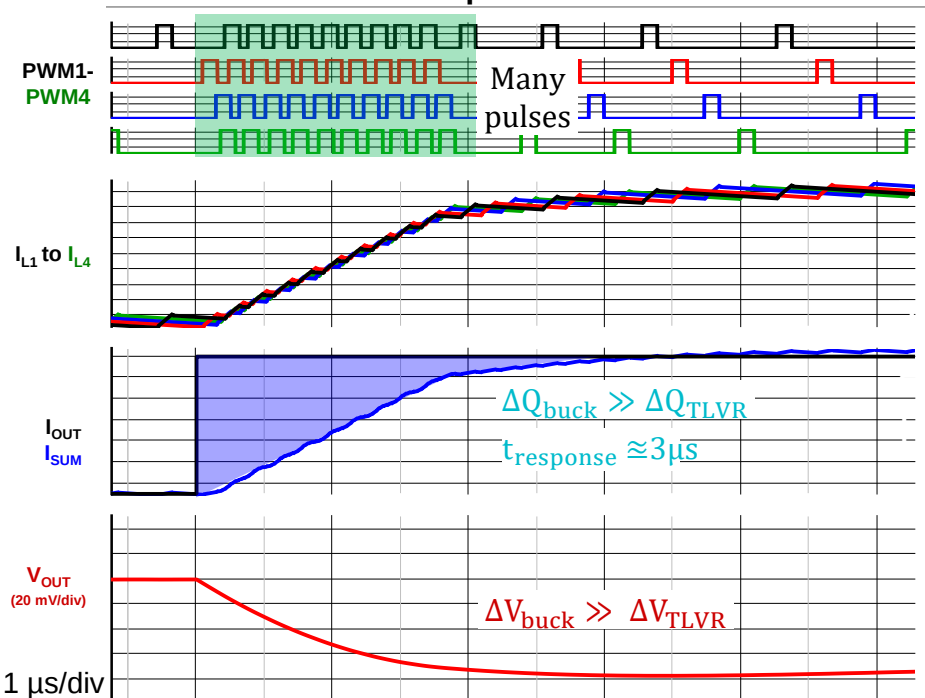
$$I_{sum}(TLVR) = (I_{Lm1} + I_{Lc}) + (I_{Lm2} + I_{Lc}) + \dots$$

$$\downarrow \text{Slope (TLVR)} = \left(\frac{\Delta V_{L1}}{L_m} + \frac{\Delta V_{Lc}}{L_c} \right) + \left(\frac{\Delta V_{L2}}{L_m} + \frac{\Delta V_{Lc}}{L_c} \right) + \dots$$

$$\downarrow \text{Slope (TLVR)} \approx \downarrow \text{Slope(buck)} - N_{total} \left[\frac{N_{total} \times V_{OUT}}{L_c} \right]$$

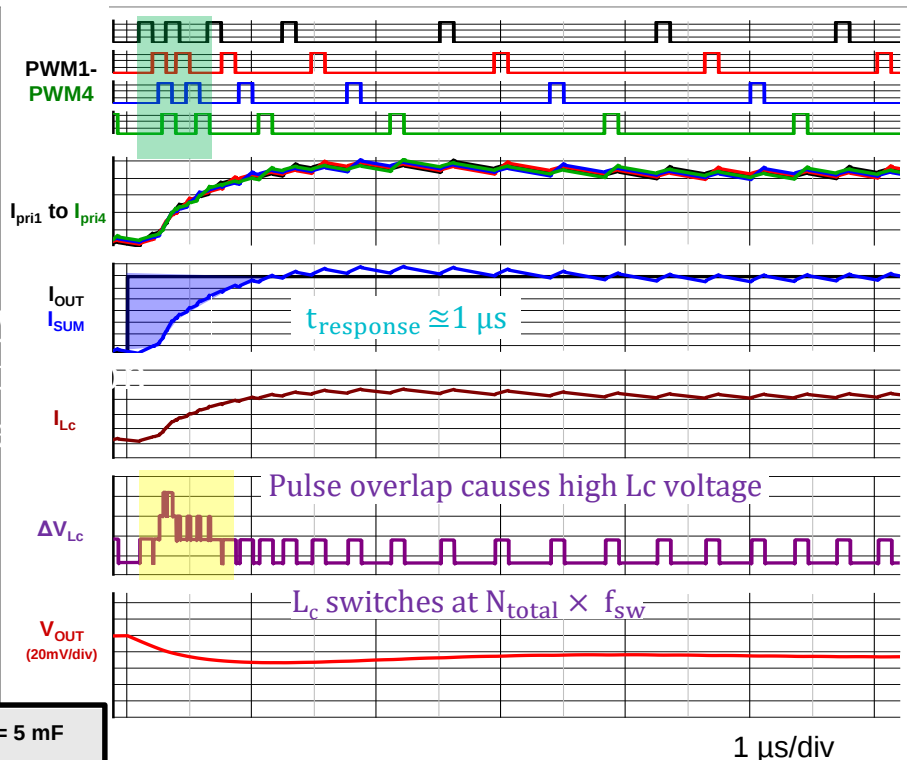
Side-by-side comparison: Load step-up

Multiphase buck



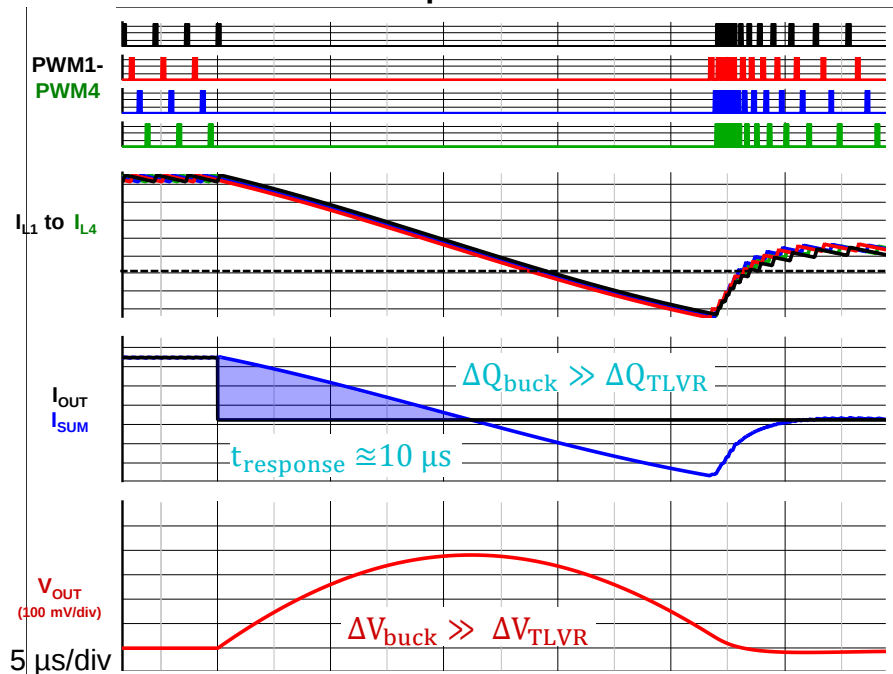
- $V_{IN} = 12 \text{ V}$
- $V_{OUT} = 0.8 \text{ V}$
- $F_{SW} = 600 \text{ kHz}$, four phases
- $I_{OUT} = 25 \text{ A}$ -325 A, instantaneous
- Buck: $L_{buck} = 150 \text{ nH}$
- TLVR: $L_m = 150 \text{ nH}$, $L_c = 180 \text{ nH}$
- $C_{OUT} = 5 \text{ mF}$

TLVR

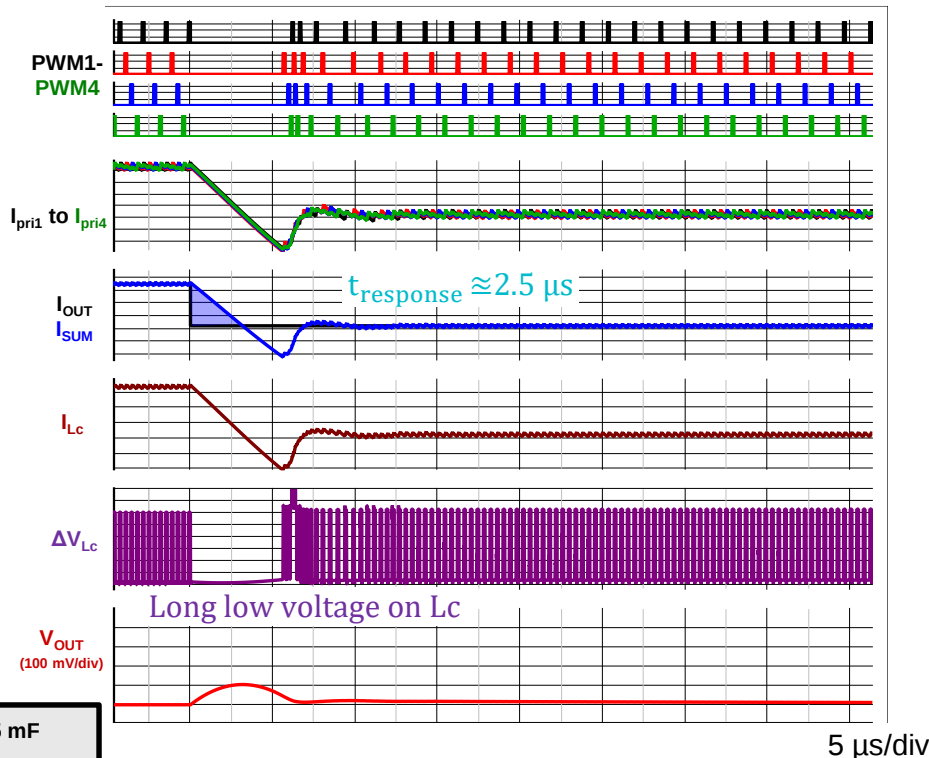


Side-by-side comparison: Load step-down

Multiphase buck



TLVR



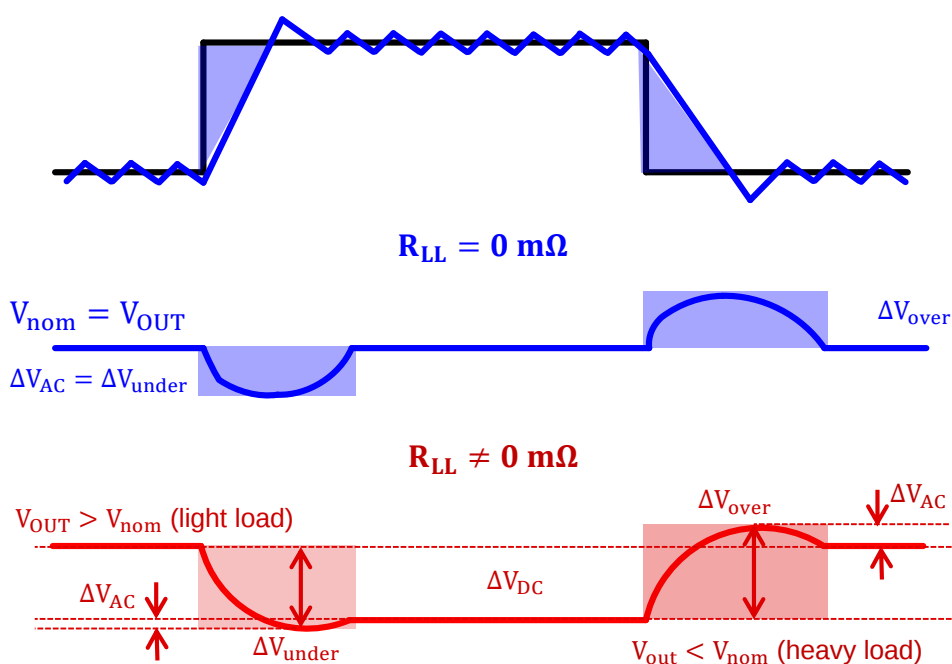
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- TLVR: $L_{\text{m}} = 150 \text{ nH}$, $L_{\text{c}} = 180 \text{ nH}$
- $C_{\text{OUT}} = 5 \text{ mF}$

5 $\mu\text{s}/\text{div}$

14

DC load line further reduces output capacitance

DC load-line (DCLL) behavior is **identical** between buck and TLVR designs



$$R_{DCLL} = \frac{\Delta V_{DC}}{\Delta I_{step}}$$

Capacitor savings

$$C_{out(min, \text{step up})} = \frac{\Delta Q_{under}}{\Delta V_{under}} = \frac{\Delta Q_{under}}{\Delta V_{ac} + R_{LL} \times I_{step}}$$

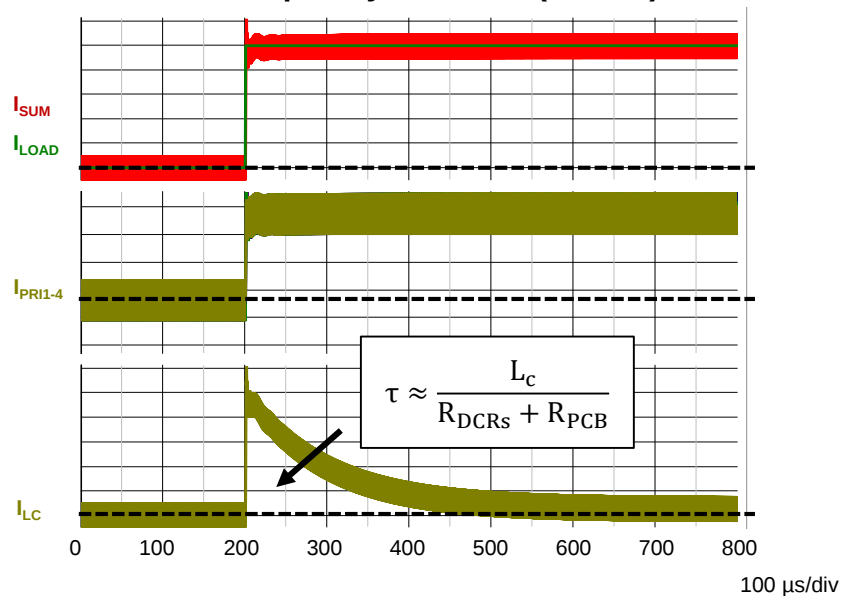
$$C_{out(min, \text{step down})} = \frac{\Delta Q_{over}}{\Delta V_{over}} = \frac{\Delta Q_{over}}{\Delta V_{ac} + R_{LL} \times I_{step}}$$

Reduced output power

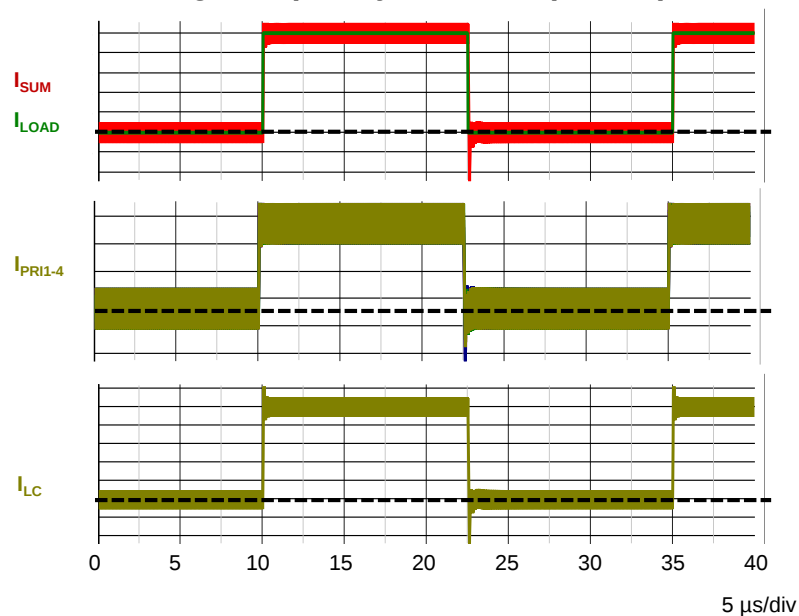
$$P_{out} = I_{out} \times (V_{out} - R_{LL} \times I_{out})$$

L_c as an AC inductor – I_{Lc} during a transient

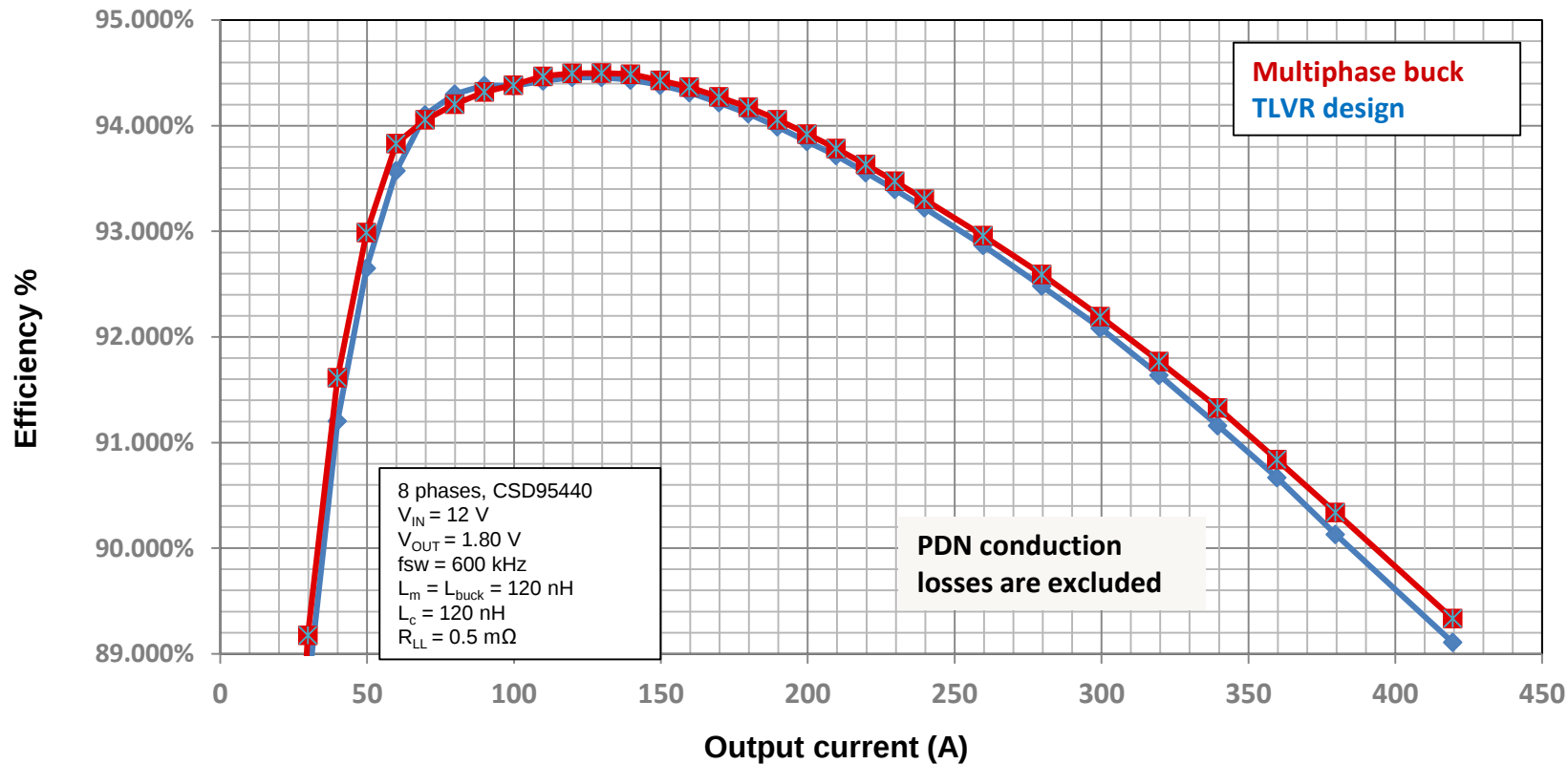
Low-frequency transient (<1 kHz)



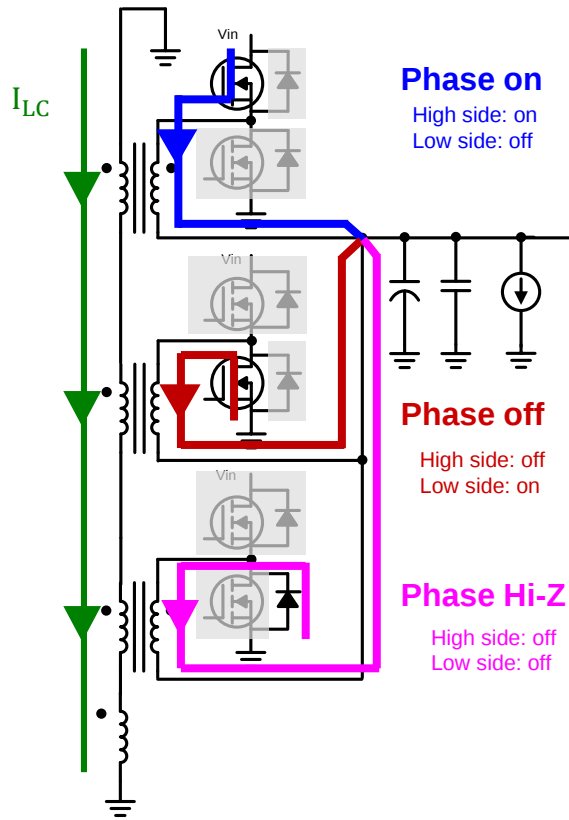
High-frequency transient (65 kHz)



VR vs. TLVR efficiency comparison ($L_{BUCK} = L_M = L_C$)



Dynamic phase shedding



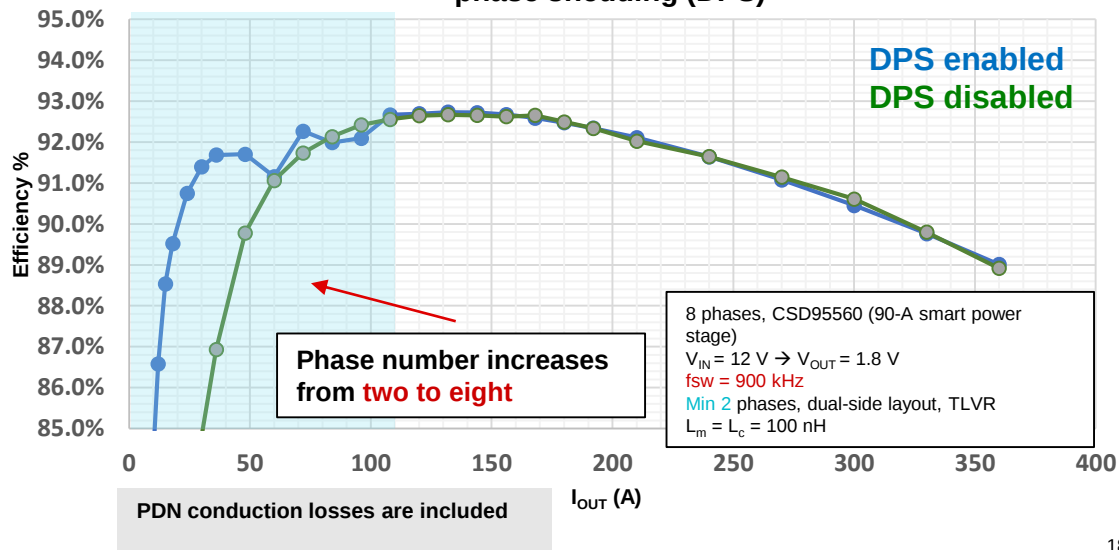
$$\Delta V_{LC} = N_{on} \times (V_{IN} - V_{OUT}) + N_{off} \times (-V_{OUT}) + N_{HiZ} \times (V_{diode})$$

$$P_{cond,HiZ} \approx I_{rms(L_C)} \times V_{diode}$$

$$P_{cond,HiZ} \ll P_{switching}$$

0 when DPS is off

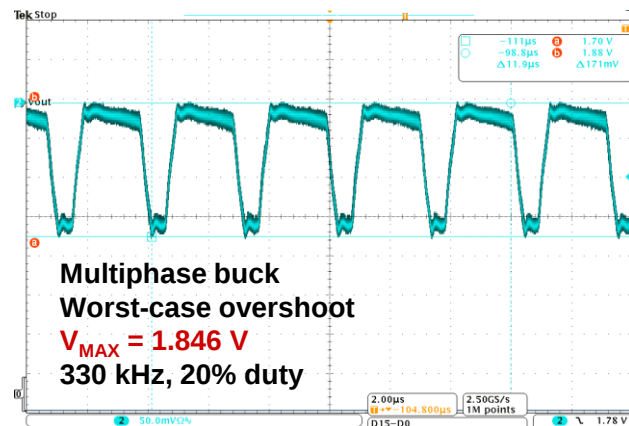
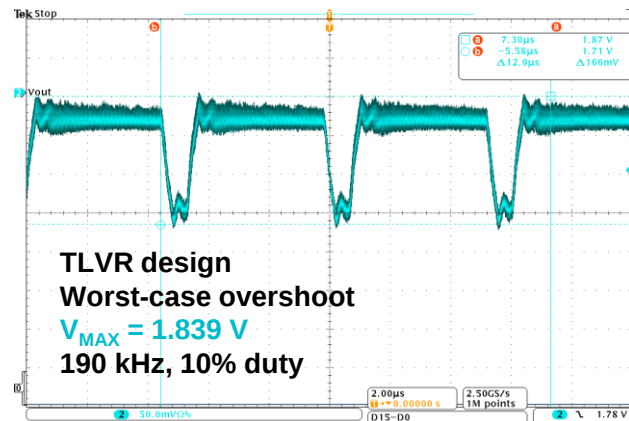
Efficiency comparison (including power delivery network [PDN]) vs. dynamic phase shedding (DPS)



Example side-by-side design

Parameter	TLVR	Multiphase buck
Controller/SPS	TPS53689, CSD95440	
V_{IN}	12 V	
V_{OUT}	1.8 V	
Number of phases	8 phases	
Switching frequency	900 kHz	
Load step	60 A-430 A, 1,000 A/ μ s, 1 kHz-1 MHz	
Load line	0.5 m Ω	
L_m/L_{buck}	150 nH	70 nH
L_c	100 nH	—
C_{bulk} (polymer)	0 $\times$ 470 μ F	5 $\times$ 470 μ F
Multilayer ceramic capacitors	80 $\times$ 22 μ F 0402	80 $\times$ 22 μ F 0402
	56 $\times$ 47 μ F 0603	45 $\times$ 47 μ F 0805
	0 $\times$ 100 μ F 0805	15 $\times$ 100 μ F 0805
	8 $\times$ 0.1 μ F 0402	8 $\times$ 0.1 μ F 0402
Total C_{out}	4.4 mF	7.7 mF

More transient margin with 45% reduction
in output capacitance required



Practical considerations

L_c inductor selection

- Typically select L_c between L_m and $1.25 \times L_m$
- Minimal root-mean-square current (RMS) required

$$I_{\text{rms}(L_c)} \approx \frac{\Delta I_{L_c}}{\sqrt{12}}$$

- High saturation current required

$$I_{\text{sat}} \gg t_{\text{resp}} \times \left[\frac{N_{\text{on(step)}} \times V_{\text{IN}} - N_{\text{total}} \times V_{\text{OUT}}}{L_c} \right]$$

- Voltage across L_c can be $\gg V_{\text{IN}}$

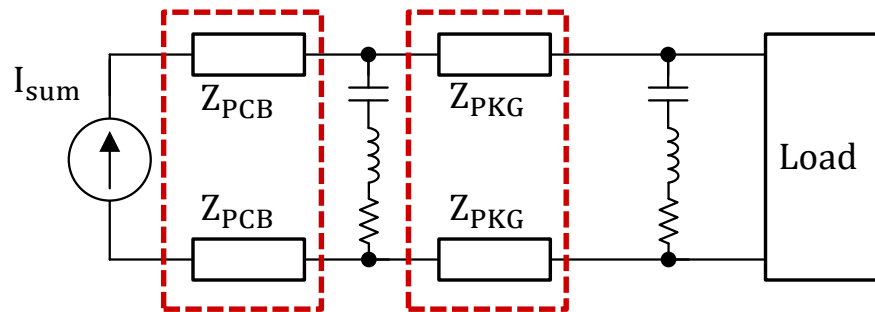
$$V_{L_c(\text{max})} = N_{\text{on(step)}} \times V_{\text{IN}} - N_{\text{total}} \times V_{\text{OUT}}$$

Example L_c selection

Parameter	Value
V_{IN}	12 V
V_{OUT}	0.8 V
F_{sw}	600 kHz
N_{total}	8 phases
L_m	150 nH
L_c	180 nH
Load transient	50-500 A, 1,000 A/μs
ΔI_{L_c}	5.0 A
F_{L_c}	4.8 MHz
$I_{\text{RMS}(L_c)}$	2.8 A
Margin for I_{SAT}	25%
$I_{\text{SAT}(\text{min})}$	75 A
$\Delta V_{L_c(\text{max})}$	30 V ($N_{\text{OVERLAP}} = 3$)

Output-ripple cancellation

Output-voltage ripple (simple model)

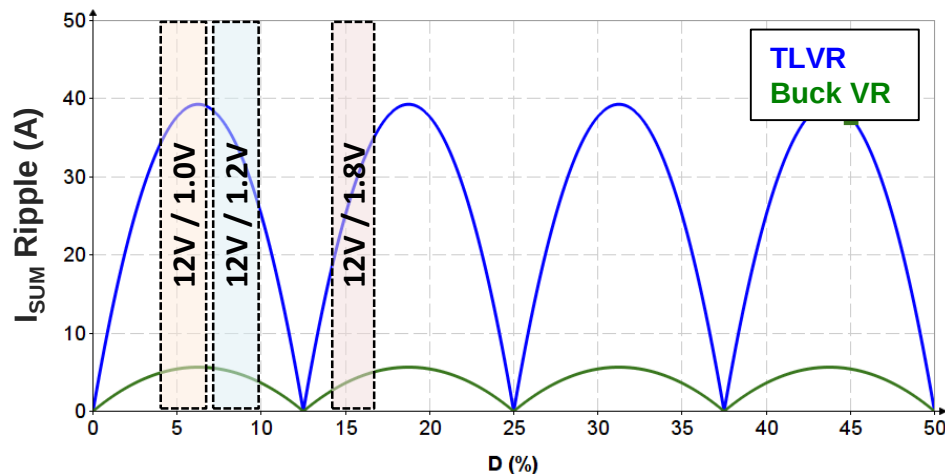


Same L_c current gets added at every phase-shift offset

$$I_{\text{sum}} = (I_{Lm1} + I_{Lc}) + (I_{Lm2} + I_{Lc}) + \dots$$

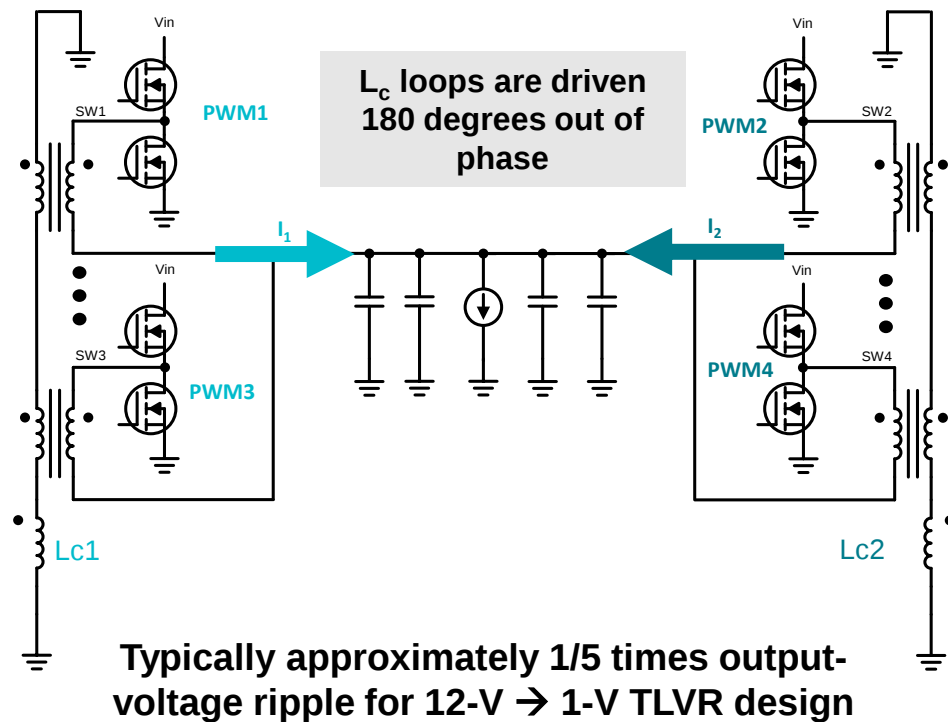
$0 \times \frac{360^\circ}{N} \text{ phase shift} \quad 1 \times \frac{360^\circ}{N} \text{ phase shift}$

Example:
TLVR vs. multiphase buck I_{OUT} ripple vs. duty cycle

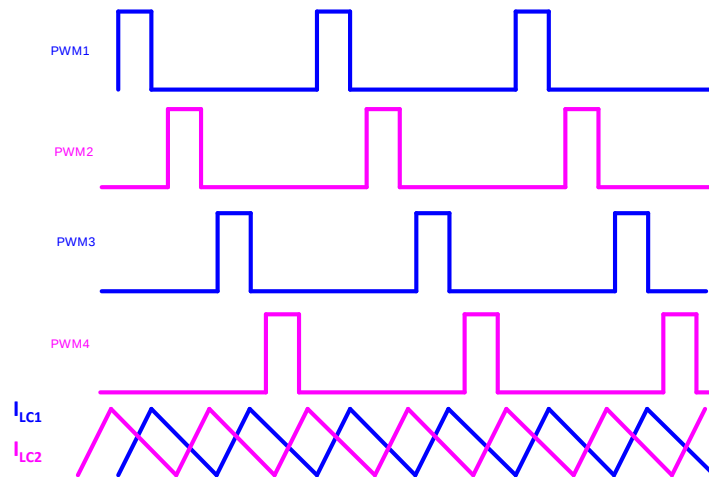


$V_{\text{IN}} = 12 \text{ V}$, $F_s = 700 \text{ kHz}$, $L_m = 150 \text{ nH}$,
 $L_c = 120 \text{ nH}$, $L_{\text{VR}} = L_{\text{eq}} = 125 \text{ nH}$, eight
 phases

Reduced ripple voltage: Interleaved TLVR

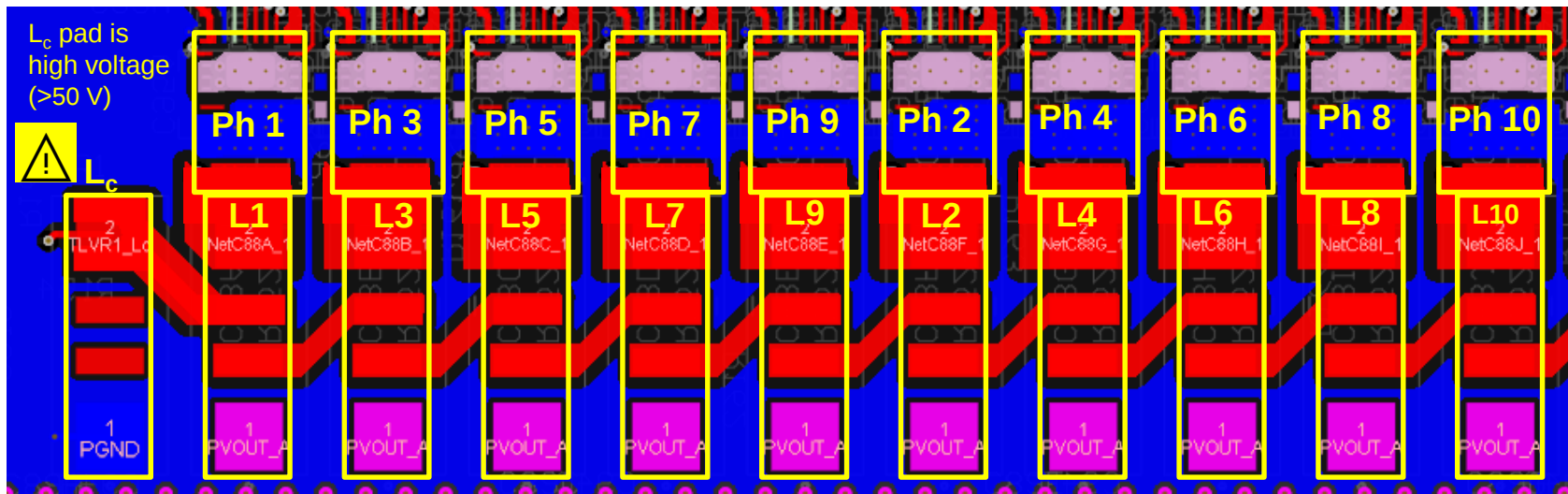


- For high-phase-count (>12 phase) designs, creating two (or more) L_c loops achieves interleaving
- May also be advantageous for layout and electromagnetic interference (EMI) concerns (reduced L_c frequency, reduced maximum L_c voltage)



Typical power-stage layout

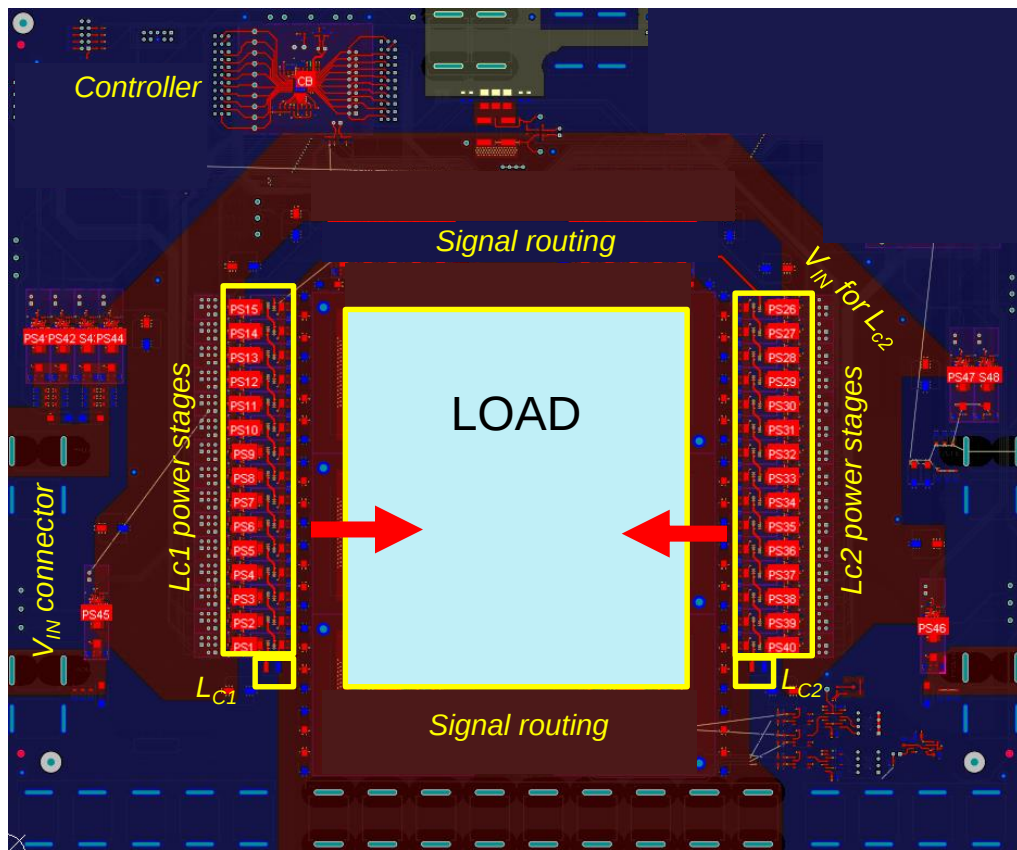
- Interleaving phase fire order reduces crosstalk and reduces input capacitor stress
- L_c current still carries high current in a transient
- Recommend ≈ 50 mils



Option for reduced EMI 1/2 L_c on each end

1/2 L_c

Printed circuit board layout: Multiside power delivery



Example:

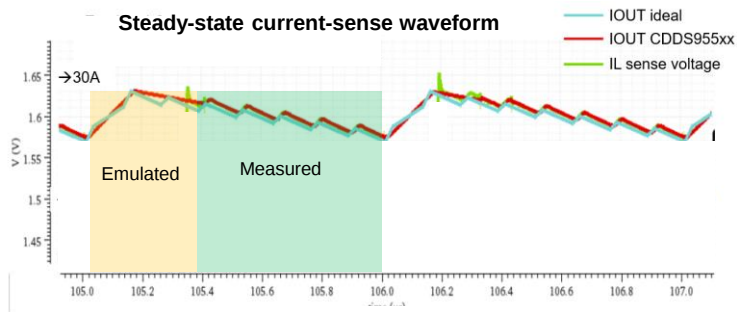
- 32-phase design
- Two L_c interleaved design

Recommendations:

- Symmetrical power train and L_c layout
- Decoupling and current-resistance (IR) drop on input traces
- PWM pin trace capacitance
 - Controller PWM drive strength
- Current-sense trace capacitance
 - Low-pass filter effect for current monitor (Imon) signals

TLVR-optimized controllers and power stages

TLVR-optimized power stages

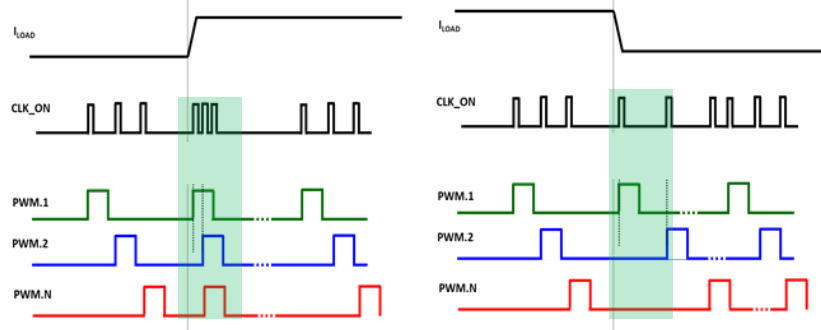


High bandwidth, real current information reporting

Part number	Current rating	Package/features
CSD95440	80-A peak, 40 A _{RMS}	5 mm × 6 mm (voltage I _{mon})
CSD95510	90-A peak, 50 A _{RMS}	4 mm × 6 mm (voltage I _{mon})
CSD95560	90-A peak, 50 A _{RMS}	4 mm × 6 mm (current I _{mon})
CSD95520	60-A peak, 30 A _{RMS}	4 mm × 5 mm (voltage I _{mon})
CSD95570	60-A peak, 30 A _{RMS}	4 mm × 5 mm (current I _{mon})

TLVR-optimized controllers

PWM-based L_c current emulation (patent pending)



Load transient detection based on PWM timing

Part number	Phases	Package/features
TPS53685	8	5 mm × 5 mm AMD interface
TPS536C5	12	6 mm × 6 mm AMD interface
TPS53689T	8	5 mm × 5 mm Intel interface
TPS536C9T	12	6 mm × 6 mm Intel interface

Conclusion

Summary

- Introduced the TLVR topology
 - Buck-derived topology similar to coupled inductors for high-phase-count designs
 - Better modularity and reuse for TLVR, since inductors do not share a core
 - Significant output capacitor savings given coupled-inductor behavior
- Practical considerations for TLVR designs
 - TLVR designs typically have higher ripple current and voltage vs. buck
 - Interleaving for high-phase-count designs
 - Printed circuit board layout for TLVR designs is similar to buck, with L_c loop added
- TLVR-optimized components
 - High-bandwidth and system-level optimizations needed to optimize for TLVR designs

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